

Position Title:	Wire Bond Technician			Position # or Level :	
Department:	Operations		Reports to:	Production Supervisor	
Employment Status:	Full Time	Pay Grade or salary range:	(List the pay grade or salary range for this position)	% Travel Required	NA

Position Summary: The Wire Bond Technician performs precision wire bonding operations on semiconductor devices and electronic components. This role requires operating wire bonding equipment, inspecting bond quality, maintaining production standards, and following manufacturing procedures to ensure high-quality products.

Essential Duties:

- Operate manual, semi-automatic, or automatic wire bonding machines
- Perform gold, aluminum wire or ribbon bonding on semiconductor devices
- Set up and adjust bonding equipment for different products and processes
- Inspect wire bonds using microscopes and other inspection equipment
- Verify bond strength, placement, and overall quality according to specifications
- Read and interpret engineering drawings, work instructions, and process documentation
- Record production data and maintain accurate manufacturing records
- Troubleshoot bonding issues and perform minor machine adjustments
- Perform routine equipment cleaning and preventive maintenance

Other Duties & Responsibilities (Optional) N/A

Minimum Qualifications:

- Must be a US Citizen or legal Permanent Resident
- Must be able to read and write in English. H.S. Diploma or equivalent
- 1–3 years of wire bonding or semiconductor manufacturing experience (preferred)
- Experience with Hesse (BJ855, BJ939), K&S, and ASM wire bonders.
- Ability to work under a microscope for extended periods

Key Competencies: Ability to work in a fast-paced team environment while applying acute attention to detail.

Level 1: Typically requires a minimum of 0-1 year of related experience

Level 2: Typically requires a minimum of 1-2 years of related experience

Level 3: Typically requires a minimum of 2-4 years of related experience

Level 4: Typically requires a minimum of 4-6 years of related experience

Preferred Skills:

- Knowledge of wedge bonding and ball bonding techniques
- Experience using bond pull testers and inspection equipment
- Familiarity with semiconductor packaging processes

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Work Environment:

Indoors, environmentally controlled. Wear common ESD and protective equipment as necessary (i.e. safety glasses, gloves). While performing the duties of the job, the employee is regularly required to sit, stand and/or walk for extended periods of time; use hands and fingers; reach with hands and arms; and talk and hear. Specific vision abilities required by this job include close vision, color vision, peripheral vision, depth perception, and the ability to adjust focus. The ability to make precisely coordinated movements of the fingers of one or both hands to grasp, manipulate, or assemble very small objects.

Employee Acknowledgement:

I have read this job description, and I fully understand all my job duties and responsibilities.

Print Name	Signature	Date	
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